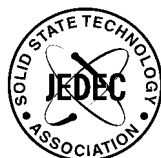


IPC/JEDEC J-STD-035
APRIL 1999

JOINT INDUSTRY STANDARD

Acoustic Microscopy
for Non-Hermetic
Encapsulated
Electronic
Components



Supersedes IPC-SM-786
Supersedes IPC-TM-650, 2.6.22

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The J-STD-035 supersedes IPC-TM-650, Test Method 2.6.22.

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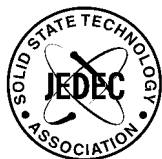
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IPC/JEDEC J-STD-035

Acoustic Microscopy for Non-Hermetic Encapsulated Electronic Components

A joint standard developed by the EIA/JEDEC JC-14.1 Committee on Reliability Test Methods for Packaged Devices and the B-10a Plastic Chip Carrier Cracking Task Group of IPC

Users of this standard are encouraged to participate in the development of future revisions.

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